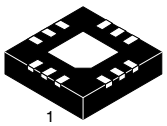
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

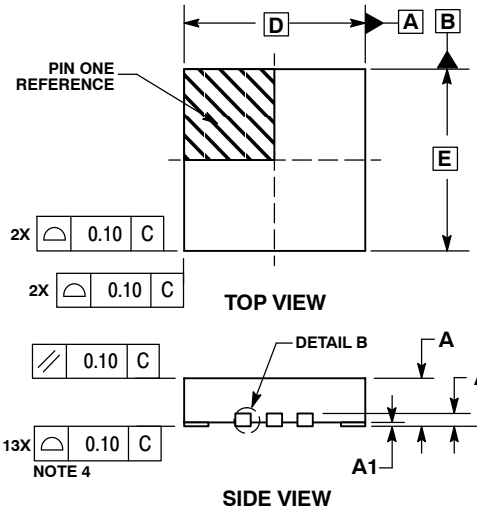
ON Semiconductor®

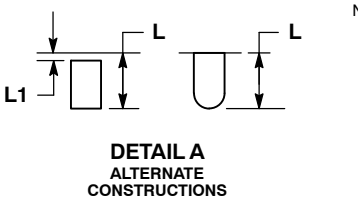
WQFN12 3x3, 0.5P
CASE 510AH−01
ISSUE O

DATE 20 JAN 2009

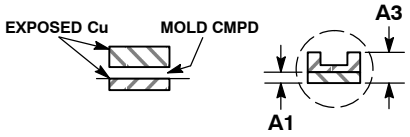


SCALE 4:1

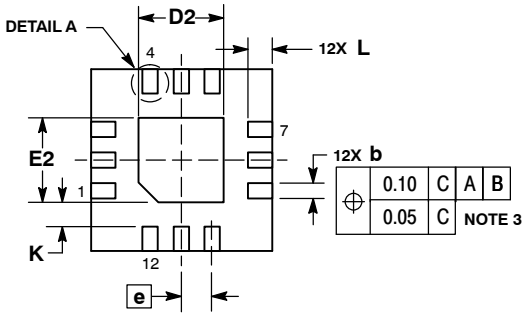




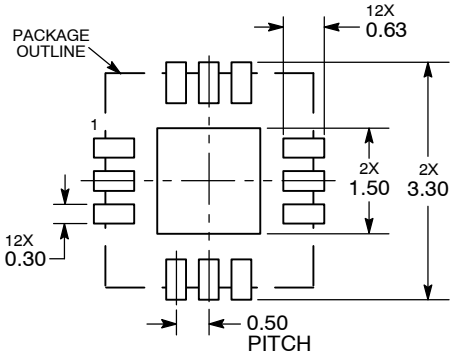
DETAIL A
ALTERNATE CONSTRUCTIONS



DETAIL B
ALTERNATE CONSTRUCTIONS



SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS	
DIM	MIN	MAX
A	0.65	0.85
A1	0.00	0.05
A3	0.22 REF	
b	0.20	0.30
D	3.00 BSC	
D2	1.30	1.50
E	3.00 BSC	
E2	1.30	1.50
e	0.50 BSC	
K	0.20	−−−
L	0.30	0.50
L1	0.00	0.15

GENERIC MARKING DIAGRAM*

XXXXX = Specific Device Code
A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
▪ = Pb−Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, "G" or microdot "▪", may or may not be present.

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STATUS:	ON SEMICONDUCTOR STANDARD		
NEW STANDARD:			
DESCRIPTION:	WQFN12, 3X3, 0.5P		PAGE 1 OF 2

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